

AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

LISTING OF CLAIMS:

Claim 1 (Currently amended): Resin coated metal foil including an insulating resin composition layer and metal foil fixed to a single surface or both the surfaces of said insulating resin composition layer, wherein:

said insulating resin composition layer contains ~~any one of cyanate resin, polyphenylene ether resin, polyamidoimide resin and epoxy resin, and a latent curing agent,~~ as principal ingredient,

surface treatment which is an anti-corrosive treatment, a chromate treatment and a silane coupling treatment is performed to at least an insulating resin composition layer side of said metal foil

a thickness of said metal foil is not more than 3 μ m, and

roughening treatment is not substantially performed to both the surfaces of said metal foil.

Claim 2 (Original): The resin coated metal foil according to claim 1, characterized in that surface roughness (Rz) of said metal foil is not more than 2.0 μ m in both the surfaces.

Claim 3 (Cancelled).

Claim 4 (Previously presented): The resin coated metal foil according to claim 1, characterized in that interfacial roughness (R_z) between said insulating resin composition layer and said metal foil is not more than $2.0\text{ }\mu\text{m}$.

Claim 5 (Cancelled).

Claim 6 (Previously presented): The resin coated metal foil according to claim 1, characterized in that said anti-corrosive treatment is performed with any one of nickel, tin, zinc, chromium, molybdenum, and cobalt or alloy thereof.

Claim 7 (Previously presented): The resin coated metal foil according to claim 1, characterized in that said insulating resin composition contains cyanate resin and said anti-corrosive treatment is performed with a metal mainly containing nickel.

Claims 8 and 9 (Cancelled).

Claim 10 (Previously presented): The resin coated metal foil according to claim 1, characterized in that a silane coupling agent used for said silane coupling treatment chemically reacts with said insulating resin composition by heating.

Claim 11 (Previously presented): The resin coated metal foil according to claim 1, characterized in that said insulating resin composition contains epoxy resin and the silane coupling agent used for said silane coupling treatment contains amino functional silane.

Claim 12 (Cancelled).

Claim 13 (Previously presented): The resin coated metal foil according to claim 1, characterized in that said insulating resin composition contains epoxy resin which is liquid at room temperatures.

Claim 14 (Cancelled).

Claim 15 (Previously presented): The resin coated metal foil according to claim 1, characterized in that, in said post-cure insulating resin composition, a relative dielectric constant is not more than 3.0 at 1 GHz or a dielectric loss tangent is not more than 0.01 at 1 GHz.

Claim 16 (Currently amended): A metal clad laminate including an insulating resin composition layer and metal foil fixed to a single surface or both the surfaces of said insulating resin composition layer, wherein:

said insulating resin composition layer contains ~~any one of cyanate resin, polyphenylene ether resin, polyamidoimide resin and epoxy resin, and a latent curing agent~~, as principal ingredient,

surface treatment which is an anti-corrosive treatment, a chromate treatment and a silane coupling treatment is performed to at least an insulating resin composition layer side of said metal foil,

a thickness of said metal foil is not more than 3 μ m, and

roughening treatment is not substantially performed to both the surfaces of said metal foil.

Claim 17 (Original): The metal clad laminate according to claim 16, characterized in that surface roughness (Rz) of said metal foil is not more than 2.0 μm in both the surfaces.

Claim 18 (Cancelled).

Claim 19 (Previously presented): The metal clad laminate according to claim 16, characterized in that interfacial roughness (Rz) between said insulating resin composition layer and said metal foil is not more than 2.0 μm .

Claim 20 (Cancelled).

Claim 21 (Previously presented): The metal clad laminate according to claim 16, characterized in that said anti-corrosive treatment is performed with any one of nickel, tin, zinc, chromium, molybdenum, and cobalt or alloy thereof.

Claim 22 (Previously presented): The metal clad laminate according to claim 16, characterized in that said insulating resin composition contains cyanate resin and said anti-corrosive treatment is performed with a metal mainly containing nickel.

Claims 23 and 24 (Cancelled).

Claim 25 (Previously presented): The metal clad laminate according to claim

16, characterized in that a silane coupling agent used for said silane coupling treatment chemically reacts with said insulating resin composition by heating.

Claim 26 (Previously presented): The metal clad laminate according to claim 16, characterized in that said insulating resin composition contains epoxy resin and the silane coupling agent used for said silane coupling treatment contains amino functional silane.

Claim 27 (Cancelled).

Claim 28 (Previously presented): The metal clad laminate according to claim 16, characterized in that said insulating resin composition contains epoxy resin which is liquid at room temperatures.

Claim 29 (Cancelled).

Claim 30 (Previously presented): The metal clad laminate according to claim 16, characterized in that, in said post-cure insulating resin composition, a relative dielectric constant is not more than 3.0 at 1 GHz or a dielectric loss tangent is not more than 0.01 at 1 GHz.

Claim 31 (Previously presented): A printed wiring board characterized by being manufactured with resin coated metal foil according to claim 1.

Claim 32 (Original): The printed wiring board according to claim 31,

characterized in that surface roughness (R_z) of a conductor circuit is not more than $2.0\text{ }\mu\text{m}$.

Claim 33 (Previously presented): The printed wiring board according to claim 31, characterized in that peel strength between said insulating resin composition layer and a conductor circuit having a width of 1 mm is not lower than 0.6 kN/m.

Claim 34 (Previously presented): The printed wiring board according to claim 31, characterized in that the peel strength between said insulating resin composition layer that has been heated at 150°C for 240 hours and the conductor circuit having the width of 1 mm is not lower than 0.4 kN/m.

Claims 35 – 40. (Cancelled).

Claim 41 (Previously presented): A printed wiring board characterized by being manufactured with a metal clad laminate according to claim 16.

Claim 42 (Previously presented): The printed wiring board according to claim 41, characterized in that surface roughness (R_z) of a conductor circuit is not more than $2.0\text{ }\mu\text{m}$.

Claim 43 (Previously presented): The printed wiring board according to claim 41, characterized in that peel strength between said insulating resin composition layer and a conductor circuit having a width of 1 mm is not lower than 0.6 kN/m.

Claim 44 (Previously presented): The printed wiring board according to claim 41, characterized in that the peel strength between said insulating resin composition layer that has been heated at 150°C for 240 hours and the conductor circuit having the width of 1 mm is not lower than 0.4 kN/m.

Claims 45 – 50. (Cancelled).

Claim 51 (Previously presented): The resin coated metal foil according to claim 2, wherein the surface roughness (Rz) of said metal foil is not more than 1.5µm in both the surfaces.

Claim 52 (Previously presented): The resin coated metal foil according to claim 2, wherein the surface roughness (Rz) of said metal foil is not more than 1.0µm in both the surfaces.

Claim 53 (Previously presented): The resin coated metal foil according to claim 1, wherein the metal foil is a copper foil.

Claim 54 (Previously presented): The metal clad laminate according to claim 16, wherein the metal foil is a copper foil.

Claim 55 (New): The resin coated metal foil according to claim 1, wherein said polyamidoimide resin is siloxane denatured polyamidoimide resin.

Claim 56 (New): A printed wiring board having a conductor circuit of three layers of first electrolytic copper layer, electroless copper layer and second electrolytic copper layer, provided on an insulating resin composition layer, wherein an interfacial roughness between said conductor circuit and said insulating resin composition layer is not more than $2\mu\text{m}$, and the peel strength is not less than 0.8 kN/m .

Claim 57 (New): The printed wiring board according to claim 56, wherein a peel strength after heat treatment at 150°C for 240 hours between said conductor circuit and said insulating resin composition layer is not less than 0.6 kN/m .

Claim 58 (New): The printed wiring board according to claim 56, wherein an electroless nickel plating layer and an electroless gold plating layer are further formed sequentially on said conductor circuit surface.

Claim 59 (New): The printed wiring board according to claim 56, wherein the thickness of said first electrolytic copper layer is not more than $3\mu\text{m}$.

Claim 60 (New): The printed wiring board according to claim 56, wherein L/S of said conductor layer is $20/20\mu\text{m}$ to $30/30\mu\text{m}$.

Claim 61 (New): The printed wiring board according to claim 56, wherein said insulating resin composition layer contains polyphenylene ether resin or polyamidoimide resin.

Claim 62 (New): The printed wiring board according to claim 56, wherein said insulating resin composition layer contains a cyanate resin, and Ni treatment is at least applied to one side of said first electrolytic copper layer contacting with said insulating resin composition layer.

Claim 63 (New): The printed wiring board according to claim 56, wherein said insulating resin composition layer contains an epoxy resin and a latent curing agent.